

ABSTRACT

METHOD OF PROCESSING WAFER

A wafer processing method includes a protective member laying step of placing a protective member on a face side of a wafer, a reverse side grinding step of grinding a reverse side of the wafer to thin the wafer, a cut groove forming step of positioning a cutting blade in alignment with projected dicing lines one at a time on the reverse side of the wafer, cutting the wafer with the cutting blade to form cut grooves in the wafer which terminate short of the face side thereof, and a cutting step of applying a laser beam to the wafer from the reverse side thereof along the cut grooves to completely sever the wafer along the projected dicing lines into individual device chips.

(Figure 6A)